

CPD32X

Schottky Rectifier Die 10 Amp, 40 Volt

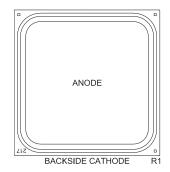
The CPD32X Schottky die is optimized for alternative energy applications. The 6 mil thick die provides an ultra low profile that is readily attached via standard die attach methods. Parametrically, the device is extremely energy efficient as a result of low forward and reverse conduction losses.

FEATURES:

- Low forward voltage at 10 Amps forward current
- Low reverse leakage current
- Low profile geometry
- Metalization suitable for standard die attach technologies
- Top metalization optimized for wire bonding

APPLICATIONS:

The CPD32X is optimized for use as a by-pass rectifier in low profile solar (PV) panels.



MECHANICAL SPECIFICATIONS:

Die Size	85.4 x 85.4 MILS			
Die Thickness	5.9 MILS ± 0.79 MILS			
Die Passivation	SiN			
Anode Bonding Pad Size	78.3 x 78.3 MILS			
Top Side Metalization	AI – 30,000Å			
Back Side Metalization	Ti/Ni/Au – 1,500Å/5,500Å/1,500Å			
Scribe Alley Width	3.15 MILS			
Wafer Diameter	5 INCHES			
Gross Die Per Wafer	2,260			

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	40	V
DC Blocking Voltage	V_{R}	40	V
Average Forward Current	IO	10	Α
Peak Forward Surge Current (tp=8.3ms)	I _{FSM}	250	Α
Operating and Storage Junction Temperature	T _J , T _{sta}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

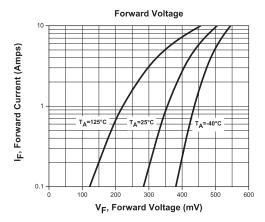
TEST CONDITIONS	'` MIN	TYP	MAX	UNITS
V _R =10V		10	200	μΑ
$V_R=40V$		30	500	μΑ
V_R =40V, T_A =100°C		15	50	mA
I _R =0.5mA	40			V
I _F =5.0A		0.43	0.48	V
I _F =10A		0.48	0.52	V
	V_{R} =10V V_{R} =40V V_{R} =40V, T_{A} =100°C I_{R} =0.5mA I_{F} =5.0A	V_{R} =10V V_{R} =40V V_{R} =40V, T_{A} =100°C I_{R} =0.5mA 40 I_{F} =5.0A	$\begin{array}{cccc} V_{R} = 10V & & 10 \\ V_{R} = 40V & & 30 \\ V_{R} = 40V, T_{A} = 100^{\circ}C & & 15 \\ I_{R} = 0.5 \text{mA} & & 40 \\ I_{F} = 5.0 \text{A} & & 0.43 \\ \end{array}$	$\begin{array}{cccccccccccccccccccccccccccccccccccc$

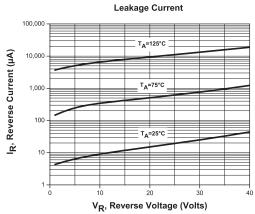
R4 (19-August 2019)

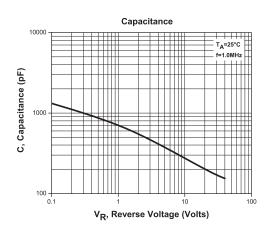
CPD32X

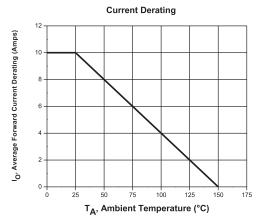
Typical Electrical Characteristics





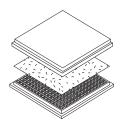






BARE DIE PACKING OPTIONS

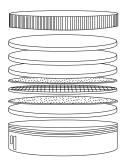




BARE DIE IN TRAY (WAFFLE) PACK

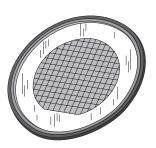
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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